

ABSTRACT OF THE DISCLOSURE

An improved structure of a chip package is disclosed. The improved structure of a chip package for used in the package structure of a digital photographic lens device with hidden chip connected with transmission lines, characterized in that the improved structure comprises a sectional of flexible circuit board and a hard thin board and the mounting legs of the photographic lens device assembly are mounted onto the flexible photographic lens device assembly having corresponding electrically connection points, and the flexible circuit board is connected to the back panel of the digital photographic lens device and is mounted with the hard thin plate.

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